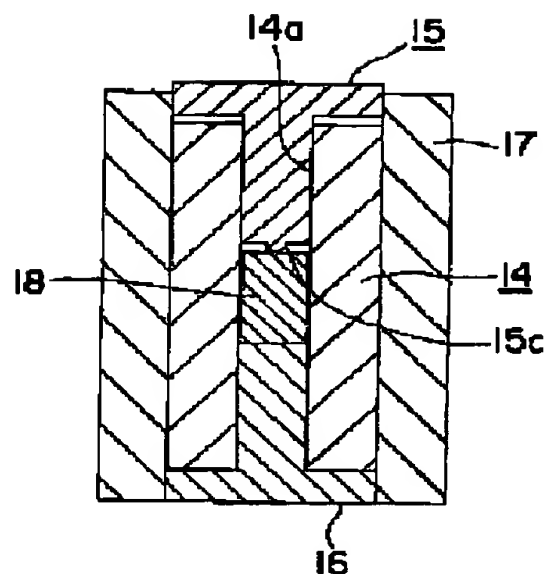


Patent Abstracts of Japan

TITLE : MOLD FOR MOLDING MOLD, ITS PRODUCTION, AND DEVICE FOR PRODUCING THE SAME



SOLUTION: The small diameter portion of a lower mold 16 is inserted into the penetrated hole 14a of a body mold 14 from its lower end opening. A member 18 to be transferred and the small diameter portion of a transfer substrate mold 15 are successively inserted into the penetrated hole 14a from its upper end opening. In a device for producing the mold, the formed set mold is heated with a heater and pressed with a press force. Thus, the molding surface 15c of the transfer substrate mold 15 is inverted and transferred to the end surface of the member 18 to be transferred in the body mold 14.

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